

Data Sheet

Liquid Encapsulation Materials

CV5313 series



Partnering to go beyond. Electronic Materials Panasonic Corporation

Specification

Liquid encapsulant materials

CV5313HS

TECHNICAL INFORMATION

This is one component epoxy for BGA/CSP reinforcement application.

TYPICAL PROPERTIES

Properties	Unit	Data	Test Method
Viscosity(25degC)	Pa*s	2	KES 0171
Thixo, index	-	1.00	KES 0170
Gelation time	sec	40	KES 0175

TYPICAL CURED PROPERTIES

Cure Conditions : 130degC 30 minutes

Properties	Unit	Data	Test Method
Glass Trans. Temp.	degC	105	KES-F-0012
C.T.E.	×10 ⁻⁵ /degC	7.1	KES 0008
Flexural Modulus	GPa	3.2	KES 0125
Volume Resistivity	ohm∙cm	1×10 ¹⁵ <	KES 0121

RECOMMED CURE CONDITIONS

130degC/5min

STORAGE

1

Shelf life	6 months(5℃>)	
Pot life (25℃70%)	3 days	

#Compound must be stored in the cool condition with sealing. (store under 5±5degC in refrigerator)

#Please keep material under 5±5degC after receiving product.

* The data in the above table are not guaranteed values.

ATTENTION TO HANDLING

#Please avoid direct contact with this product by wearing gloves, protecting gears,etc.#Prevent frequent skin contact. If contact occurs, wash immediately with soap and water.



++ Before purchase ++

[Notes before you use]

- Please verify the suitability and fitness for intended application by quality testing, evaluation or other means at your own option before any adoption, use or change of use conditions of a product listed in the datasheet.
- •We would like to have a delivery specifications mutually agreed for the product that you have decided to use. The agreements defined in the delivery specifications are assigned higher priority.
- Please note that specifications and external design are subject to change for product improvement without notice.
- For details on products in the datasheet, please contact your distributor or our sales department.

[Safety Information]

- •Before using the product, please read the delivery specifications carefully or contact the distributor from which you purchased the product or our sales department in order to use the product correctly.
- The products in the datasheet are Semiconductor encapsulation materials for electronic and electrical devices. Please do not use them for other than specified use.

Please Contact us of more

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